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(71)Applicant : **HITACHI CHEM CO LTD**

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(72)Inventor : **ABE TAKUJI**

OTOMO SATOSHI

ITAGAKI KATSUTOSHI

ICHIKAWA TATSUYA

(54) PHOTOSENSITIVE RESIN COMPOSITION, PHOTOSENSITIVE ELEMENT, METHOD FOR PRODUCING RESIST PATTERN AND METHOD FOR PRODUCING PRINTED WIRING BOARD

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a photosensitive resin composition excellent in photosensitivity, resolution, adhesion and solubility in a developing solution and a photosensitive element using the composition.

SOLUTION: The photosensitive resin composition comprises (A) a binder polymer, (B) a photopolymerizable monomer containing an ethylenically unsaturated group, (C) a polycyclic aromatic hydrocarbon, (D) a photopolymerization initiator and (E) a hydrogen donor. The photosensitive element is obtained by forming a resist layer comprising the photosensitive resin



composition on a support.

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